



Motion Specifications	SVA DEV	SVA 3000
X/Y Accuracy	± 10 µm (± 5µm)	± 5 µm
X/Y Bidirectional Repeatability	± 1 µm	± 2 µm
X/Y Maximum Acceleration	0.5g (no load)	2g (no load)
X/Y Maximum Speed	300 mm/s	500 mm/s
X/Y Travel Range	300 x 150 mm	300 x 300 mm
X/Y Resolution	100 nm	5 nm
Z Accuracy	± 6 µm (± 5µm)	± 5 µm
Z Bidirectional Repeatability	± 1 µm	± 0.7 µm
Z Maximum Speed	50 mm/s	100 mm/s
Z Travel Range	100 mm	150 mm
Z Resolution	100 nm	
Dimensions	38 x 36 x 48" 97 x 92 x 122 cm	44 x 37 x 69" 112 x 94 x 176 cm
Weight	400 lbs. 185 kg	1750 lbs. 795 kg
Features	SmartPump™100 Real-Time Process View, nVision AutoCal Pit, Auto Clean Pit	Gantry System with SmartPump™100, Real-Time Process View, nVision AutoCal Pit, Auto Clean Pit, Tray Handling
Additional Options	Overhead HEPA Filtration, Post-Process Inspection	

The SVA Series is a set of tools that are capable of precision micro-dispensing of solder paste, adhesive materials, and filling vias. This multi-function tool comes in standard sizes of 1500 and 3000 each number representing the adhesive/solder dots and VIA fillings per hour. The SVA 3000 is a SMEMA standard tool for in line production. This series is top of line for industrial manufacturing and can consistently print small features including solder dots down to 50 microns, conductive traces of 30 microns, and adhesives and dielectrics down to 20 microns. The SVA series also has the capability to fill vias with 25 micron diameter.

